

### Strain Gage Adhesive



#### OTHER ACCESSORIES USED IN AN M-BOND AE-10 INSTALLATION:

- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- PCT-2M Gage Installation Tape
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

#### DESCRIPTION

Two-component, 100%-solids epoxy system for general-purpose stress analysis. Transparent, medium viscosity. Cure time as low as six hours at +75°F [+24°C] may be used. Elevated-temperature postcure is recommended for maximum stability, and/or tests above room temperature.

Highly resistant to moisture and most chemicals, particularly when postcured. For maximum elongation, bonding surface must be roughened. Cryogenic applications require very thin gluelines.

#### CHARACTERISTICS

##### Operating Temperature Range:

**Long Term:** -320° to +200°F [-195° to +95°C].

##### Elongation Capabilities:

1% at -320°F [-195°C];  
6% to 10% at +75°F [+24°C];  
15% at +200°F [+95°C].

##### Shelf Life:

12 months at +75°F [+24°C]; 18 months at +20°F [-7°C]. If crystals form in resin jar, heat to +120°F [+50°C] for 30 minutes. Cool before mixing.

##### Pot Life:

15 to 20 minutes at +75°F [+24°C]. Can be extended by cooling jar or by spreading adhesive on clean aluminum plate.

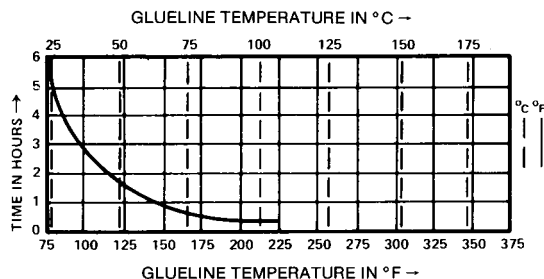
##### Clamping Pressure:

5 to 20 psi [35 to 140 kN/m<sup>2</sup>].

##### Cure Requirements:

**Preferred Room-Temperature Cure:** 24-48 hours at +75°F [+24°C].

**Recommended Postcure:** 2 hours at 25°F [15°C] above maximum operating temperature.



#### PACKAGING

##### Kit:

6 mixing jars [10 g ea] Resin  
1 bottle [15 ml] Curing Agent 10  
6 calibrated pipettes  
6 stirring rods

##### Bulk:

200 g Resin  
40 g Curing Agent 10  
3 calibrated pipettes

**References:** Instruction Bulletin B-137, "Strain Gage Applications with M-Bond AE-10, AE-15, and GA-2 Adhesive Systems", included in each kit.